



HBN25T120-SAOCH

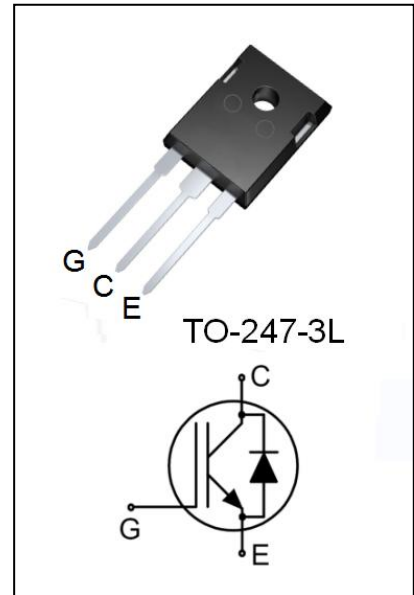
1200V N-Channel Insulated Gate Bipolar Transistor

● **Features:**

- 25.0A, 1200V, $V_{CESAT(Typ)} = 2.1V @ V_{GE} = 15V, I_C = 25A$
- Trench FS Technology
- With Fast Recovery anti-parallel Diode
- Low Gate Charge
- Low Saturation Voltage
- Low Switching Loss
- Positive Temperature Coefficient

● **Application:**

- General Purpose Inverters
- Welding Machine
- UPS



Absolute Maximum Ratings($T_c = 25^\circ C$ unless otherwise noted)

Symbol	Parameter	Value	Unit
V_{CE}	Collector-Emitter Voltage	1200	V
I_C	Collector Current-Continuous - ($T_c = 25^\circ C$) - ($T_c = 100^\circ C$)	50	A
		25	A
I_{CM}	Collector Current – Pulse (Note1)	75	A
I_F	Diode Forward Current - ($T_c = 25^\circ C$) - ($T_c = 100^\circ C$)	25	A
		12.5	A
I_{FSM}	Surge non Repetitive Forward Current $t_p = 10ms$ Sinusoidal	37.5	A
V_{GE}	Gate-Emitter Voltage	± 20	V
P_D	Power Dissipation($T_c = 25^\circ C$)	205	W
T_j	Operating Junction Temperature	150	$^\circ C$
T_{stg}	Storage Temperature Range	-55 to +150	$^\circ C$

*Collector Current Limited by Maximum Junction Temperature.

Thermal Characteristics

Symbol	Parameter	Max	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case for IGBT	0.61	$^\circ C / W$
$R_{\theta JC}$	Thermal Resistance, Junction to Case for Diode	1.55	$^\circ C / W$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	39	$^\circ C / W$



HBN25T120-SAOCH

1200V N-Channel Insulated Gate Bipolar Transistor

Electrical Characteristics(Tc=25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Off Characteristics						
BV_{CES}	Collector-Emitter Breakdown Voltage	$V_{GE}=0V, I_C=1mA$	1200	--	--	V
I_{CES}	Zero Gate Voltage Collector Current	$V_{CE}=1200V, V_{GE}=0V$	--	--	500	μA
I_{GESF}	Gate-Body Leakage Current, Forward	$V_{GE}=+20V, V_{CE}=0V$	--	--	400	nA
I_{GESR}	Gate-Body Leakage Current, Reverse	$V_{GE}=-20V, V_{CE}=0V$	--	--	-400	nA
On Characteristics						
$V_{GE(th)}$	Gate Threshold Voltage	$V_{CE}=V_{GE}, I_C=1mA$	5.0	6.6	8.0	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$V_{GE}=15V, I_C=25A$	--	2.1	2.7	V
Dynamic Characteristics						
C_{ies}	Input Capacitance	$V_{CE}=30V, V_{GE}=0V, f=1.0MHz$	--	2770	--	pF
C_{oes}	Output Capacitance		--	85	--	pF
C_{res}	Reverse Transfer Capacitance		--	19	--	pF
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	$V_{CE}=600V, I_C=25A, R_G=10\Omega, V_{GE}=15V, \text{Inductive Load}$	--	30	--	ns
t_r	Turn-On Rise Time		--	78	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	68	--	ns
t_f	Turn-Off Fall Time		--	109	--	ns
E_{on}	Turn-On Energy		--	2.3	--	mJ
E_{off}	Turn-off Energy		--	0.42	--	mJ
E_{ts}	Total Switching Energy		--	2.72	--	mJ
Q_g	Total Gate Charge	$V_{CE}=600V, I_C=25A, V_{GE}=15V$	--	92	--	nC
Q_{ge}	Gate-Emitter Charge		--	31	--	nC
Q_{gc}	Gate-Collector Charge		--	30	--	nC
Anti-Parallel Diode Characteristics and Maximum Ratings						
V_F	Collector-Emitter Diode Forward Voltage	$I_F=12.5A, T_C=25^\circ C$	--	2.0	2.7	V
		$I_F=12.5A, T_C=125^\circ C$	--	1.8	--	V
t_{rr}	Diode Reverse Recovery Time	$I_{EC}=10A$	--	73	--	ns
Q_{rr}	Diode Reverse Recovery Charge	$dI_{EC}/dt=100A/\mu s$	--	127	--	nC

Notes:

- 1、Repetitive Rating:Pulse Width Limited by Maximum Junction Temperature.

Typical Performance Characteristics

Fig 1. Output Characteristic

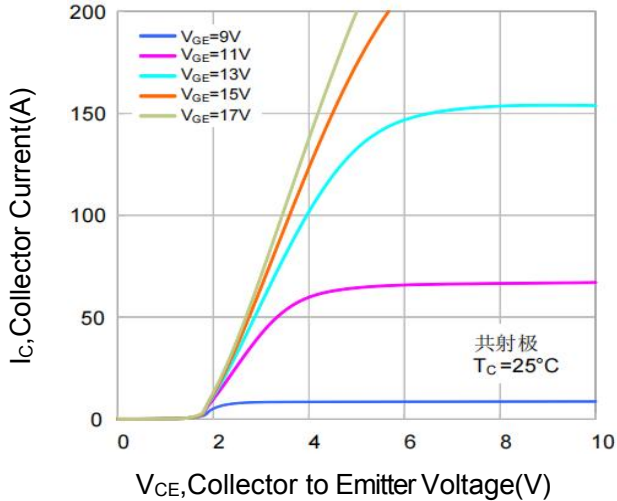


Fig 2. Output Characteristic

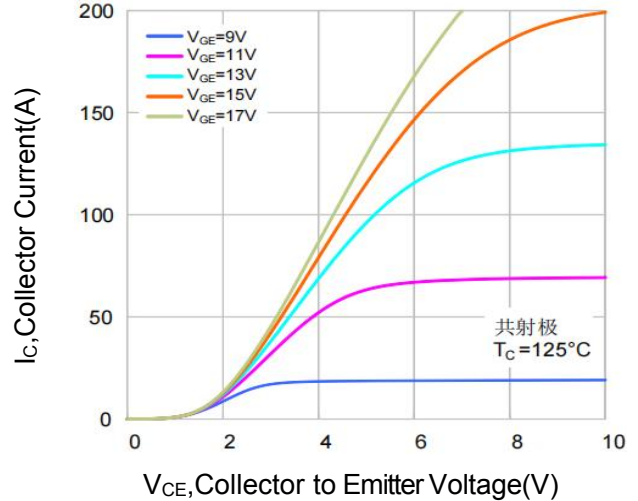


Fig 3. Saturation Voltage Characteristic

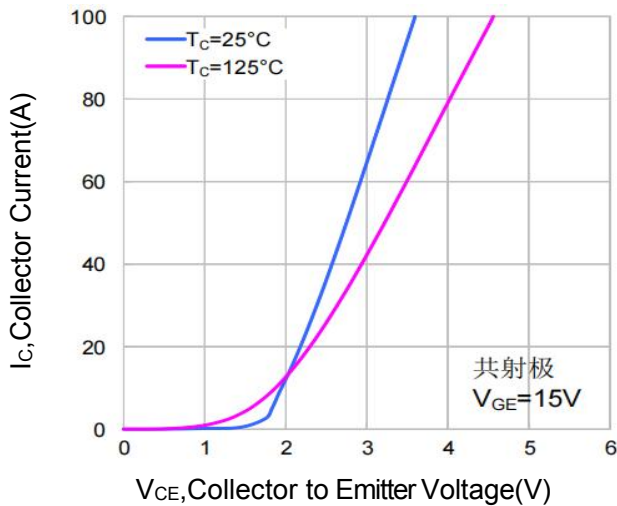


Fig 4. Transfer Characteristic

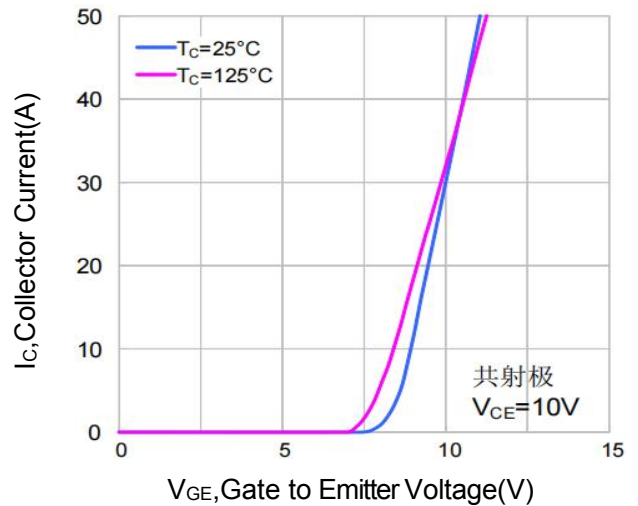


Fig 5. $V_{CE(sat)}$ vs. V_{GE} (V)

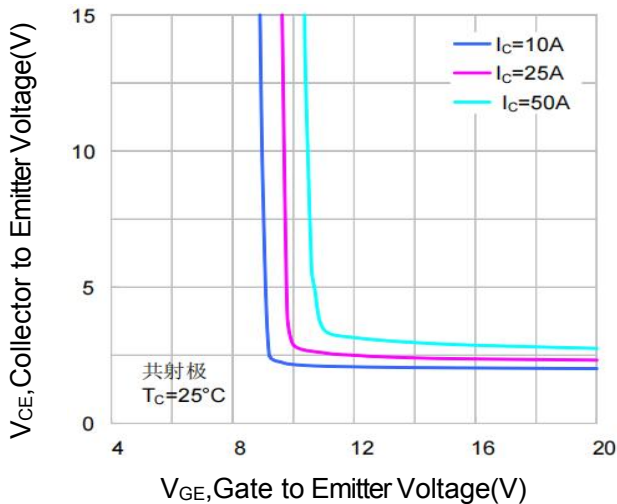


Fig 6. $V_{CE(sat)}$ vs. V_{GE} (V)

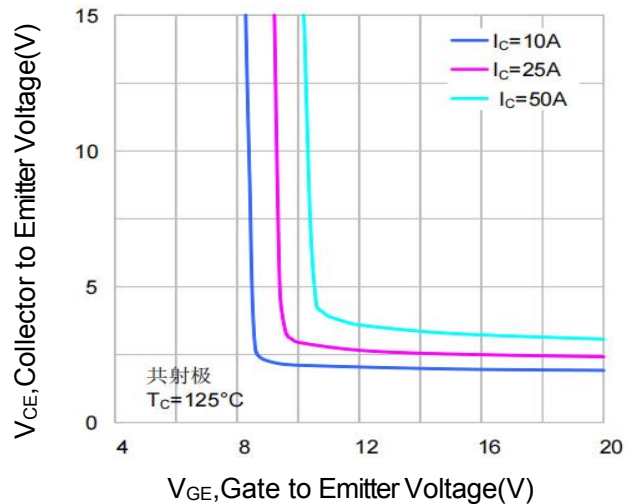


Fig 7. $V_{CE(sat)}$ vs. T_c

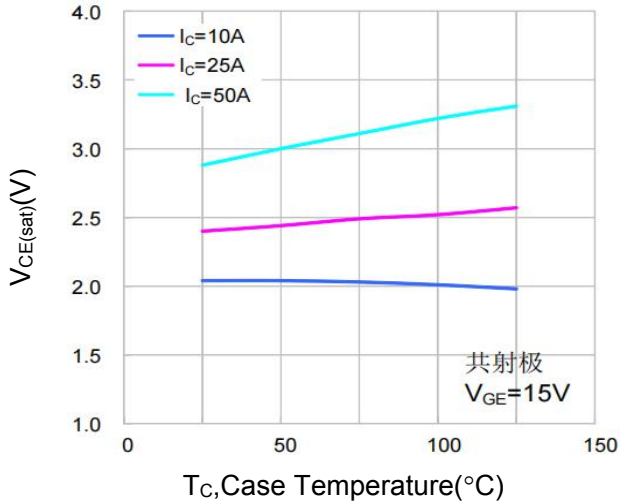


Fig 8. Capacitance Characteristic

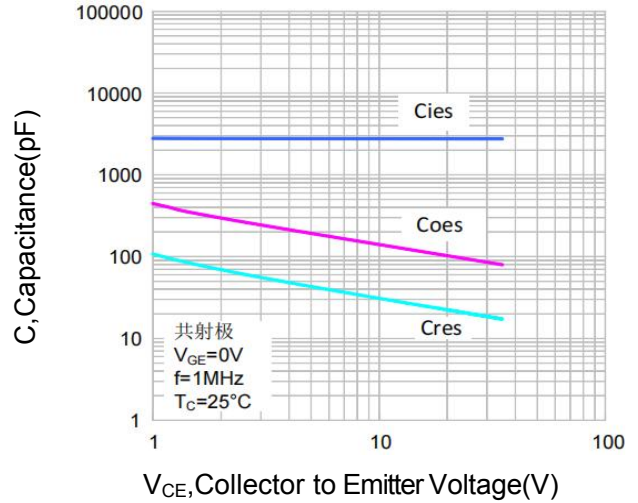


Fig 9. Gate Charge Characteristics

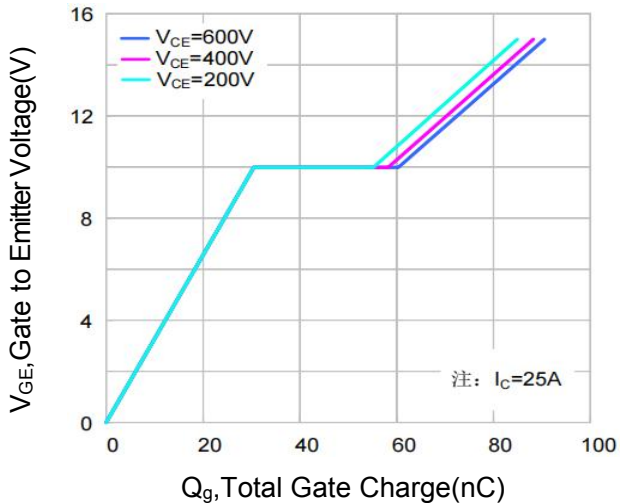


Fig 10. Switching Time vs. R_g

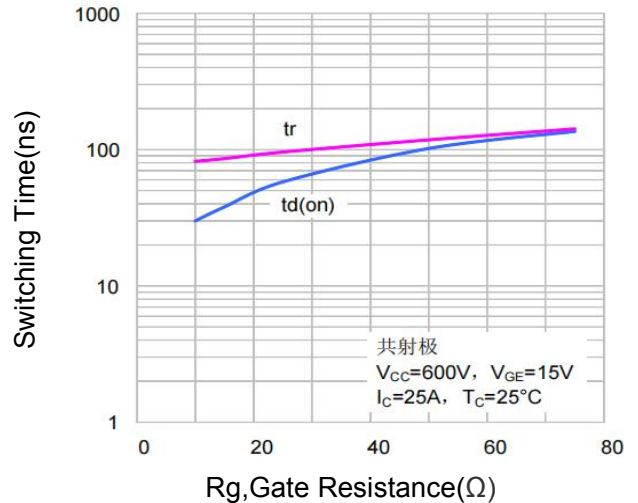


Fig 11. Switching Time vs. R_g

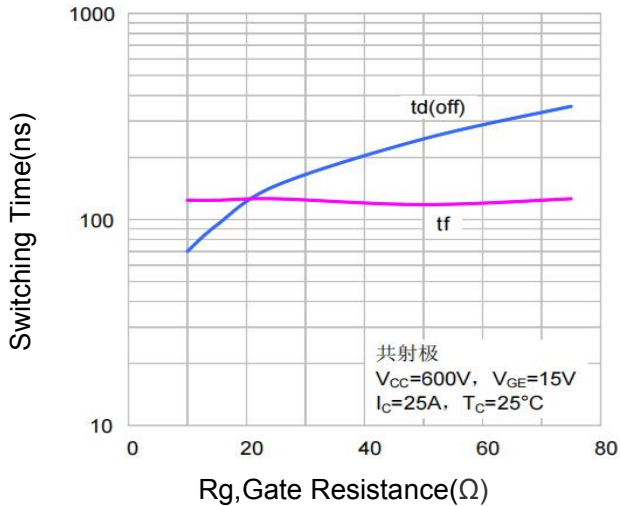


Fig 12. Switching Loss vs. R_g

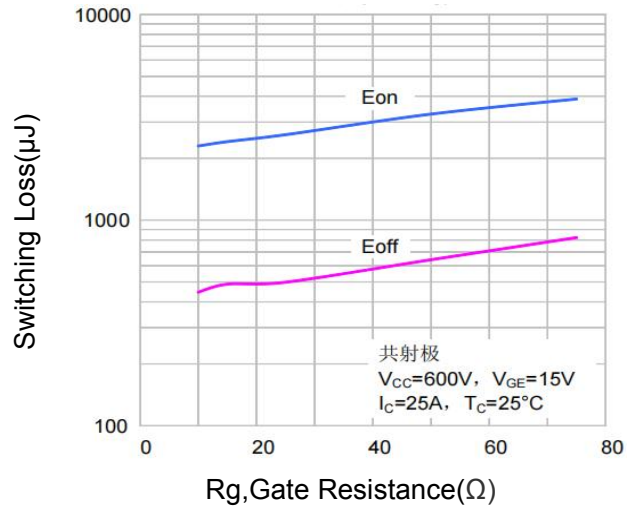


Fig 13. Switching Time vs. I_c

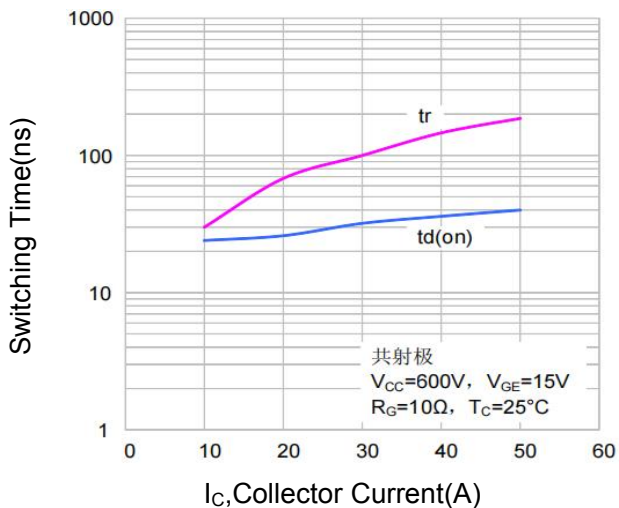


Fig 14. Switching Time vs. I_c

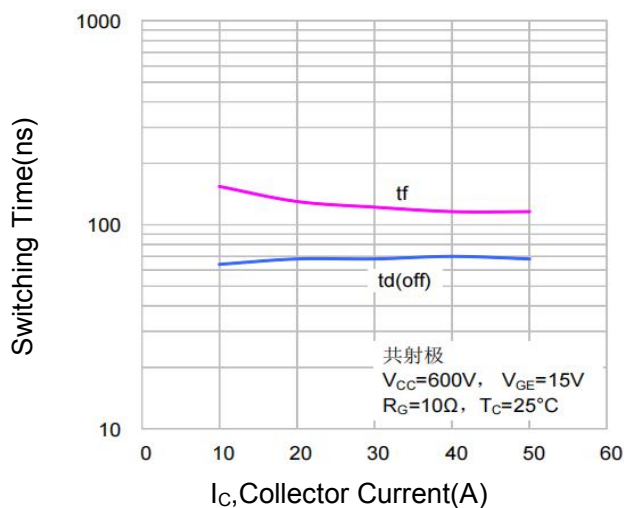


Fig 15. Switching Loss vs. I_c

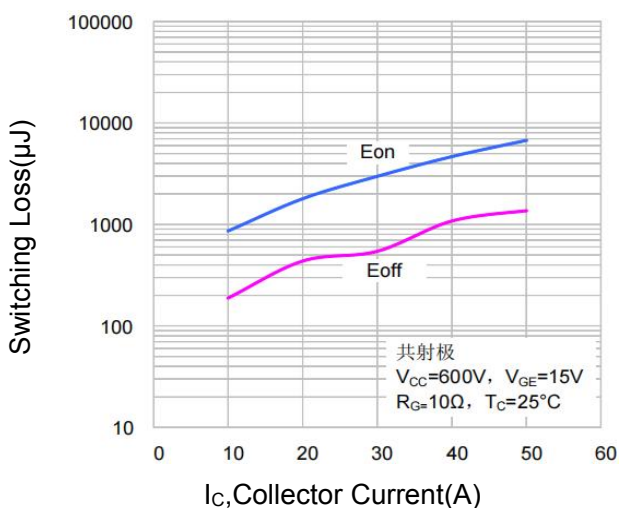


Fig 16. Diode Forward Characteristic

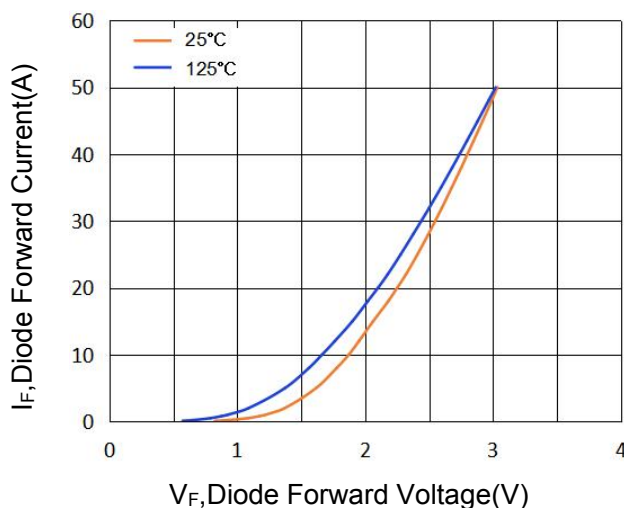


Fig 17. Safe Operating Area

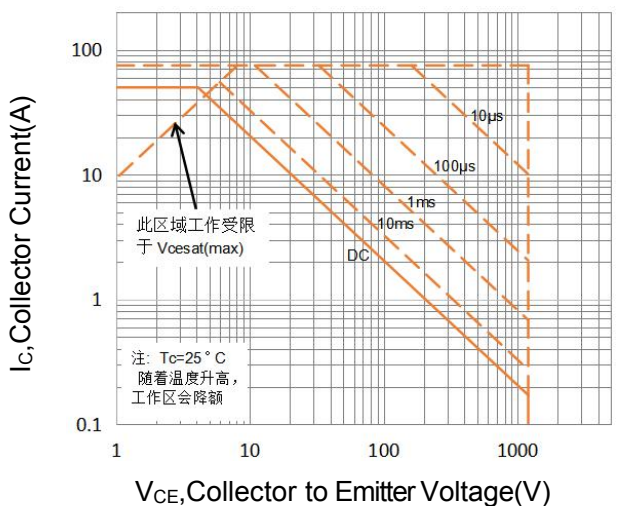
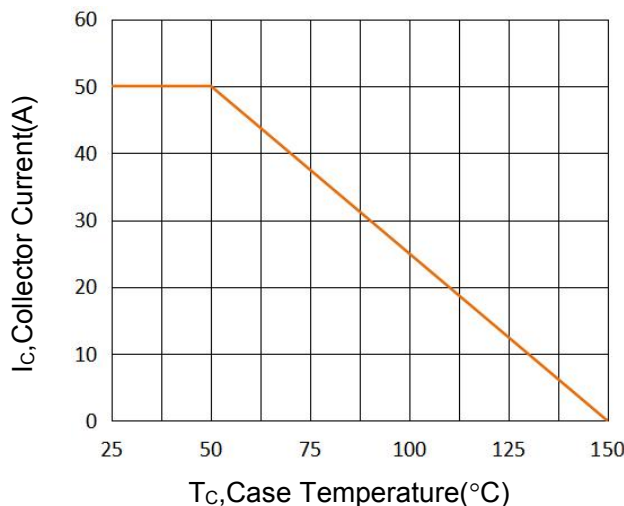


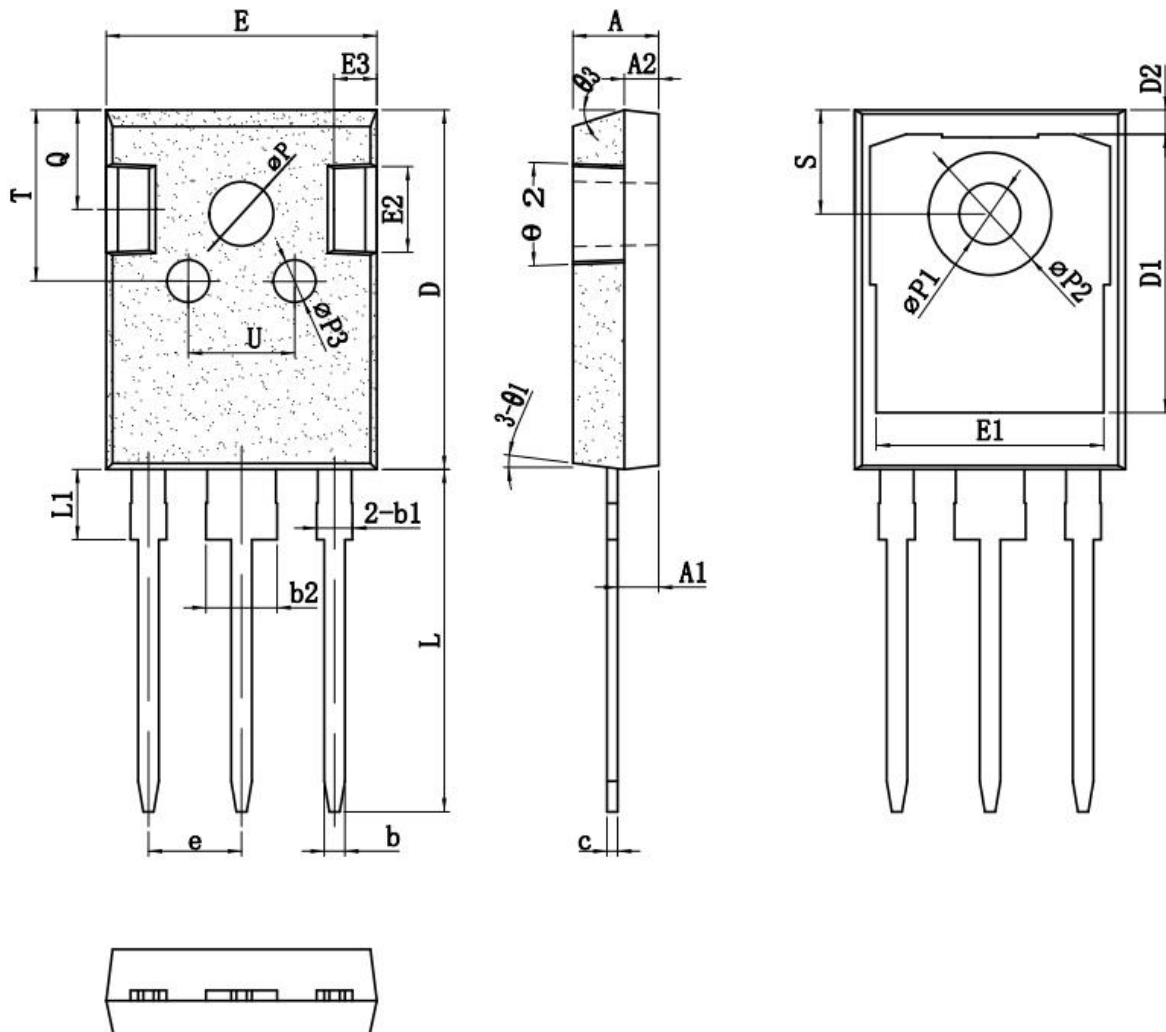
Fig 18. I_c vs T_C



TO-247-3L Package Dimensions

UNIT: mm

SYMBOL	min	nom	max	SYMBOL	min	nom	max
A	4.70	5.00	5.30	e	--	5.44	--
A1	2.20	2.40	2.60	L	19.00	20.00	21.00
A2	1.80	2.00	2.20	L1	3.90	4.30	4.70
b	1.00	1.20	1.40	ΦP	3.40	3.60	3.80
b1	1.90	2.10	2.30	$\Phi P1$	3.30	3.50	3.70
b2	2.90	3.10	3.30	$\Phi P2$	6.88	7.18	7.48
c	0.50	0.60	0.70	$\Phi P3$	2.20	2.50	2.80
D	20.50	21.00	21.50	Q	5.30	5.80	6.30
D1	15.50	16.50	17.50	S	5.65	6.15	6.65
D2	0.90	1.20	1.50	T	9.00	10.00	11.00
E	15.30	15.80	16.30	U	5.20	6.20	7.20
E1	12.75	13.25	13.75	$\theta 1$	5°	7°	9°
E2	4.70	5.00	5.30	$\theta 2$	1°	3°	5°
E3	2.20	2.50	2.80	$\theta 3$	13°	15°	17°





HBN25T120-SAOCH

1200V N-Channel Insulated Gate Bipolar Transistor

注意事项:

- 1、在电路设计时请不要超过器件的最大额定值，否则会影响整机的可靠性。
- 2、IGBT产品为静电敏感型器件，使用时应注意采取防静电保护措施，如佩戴防静电手环、设备接地等。
- 3、如需安装散热片，请注意控制扭力大小及散热片的平整度。
- 4、该规格书由华科公司制作，并可能不定期更改，恕不另行通知。
- 5、如有疑问，请及时联系我司销售代表。

版本履历表:

序号	版本号	修改时间	修改记录
1	V1.0	2023-3-22	首次发行